

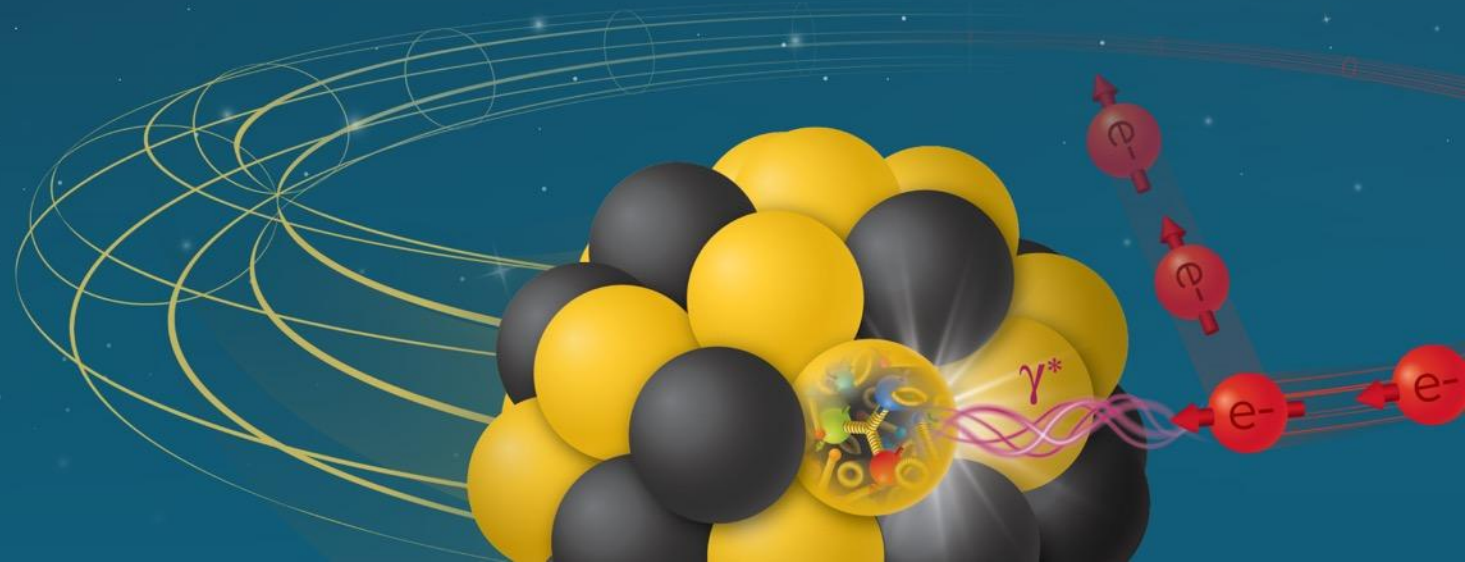
# MPGDs: Power and Cooling Design

**Seungjoon Lee**

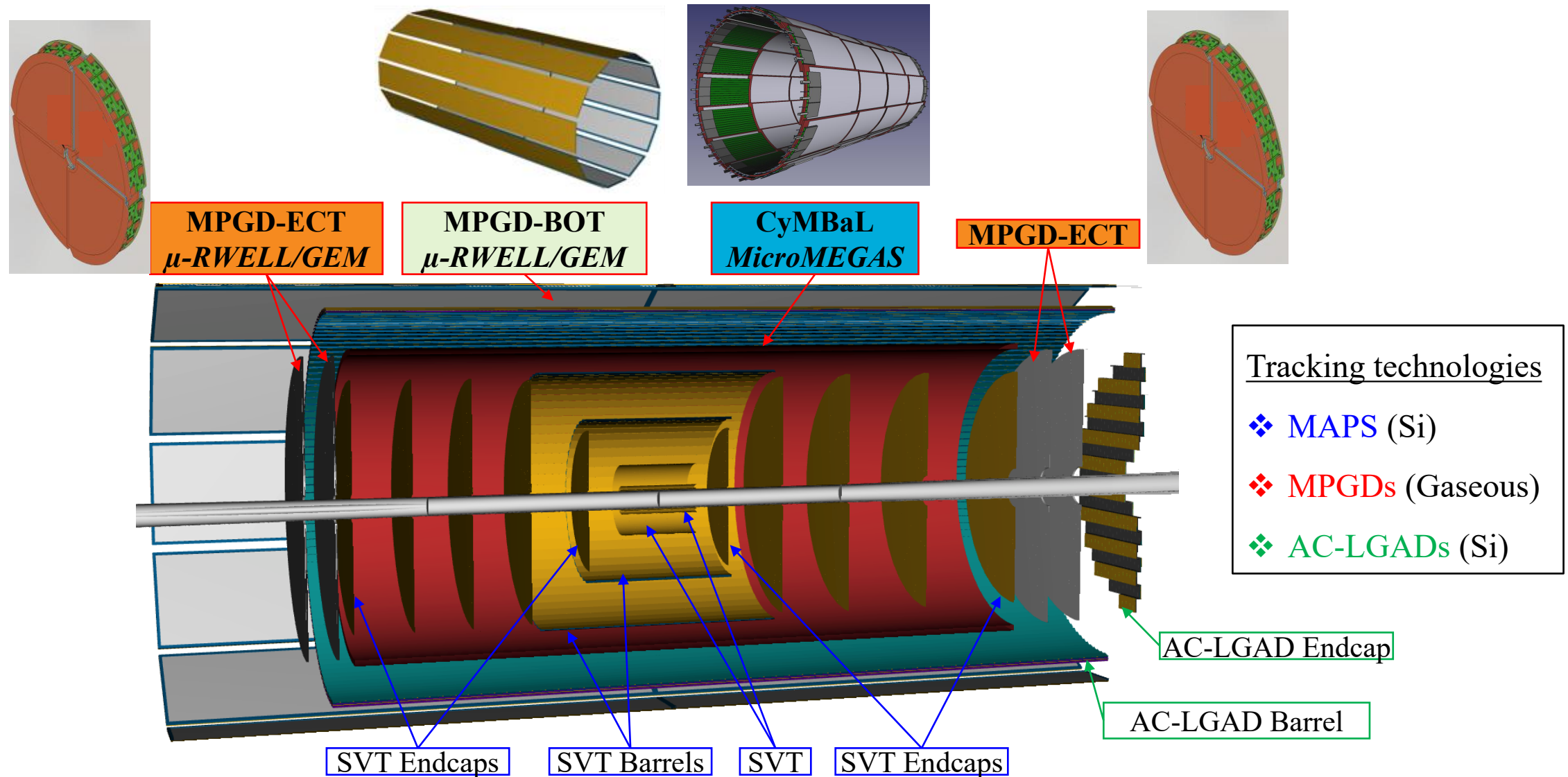
Outer MPPD Engineer (Jefferson Lab - RD&I Group)

ePIC Collaboration Meeting  
Brookhaven National Laboratory, US  
Jan 20-23, 2026

Electron-Ion Collider

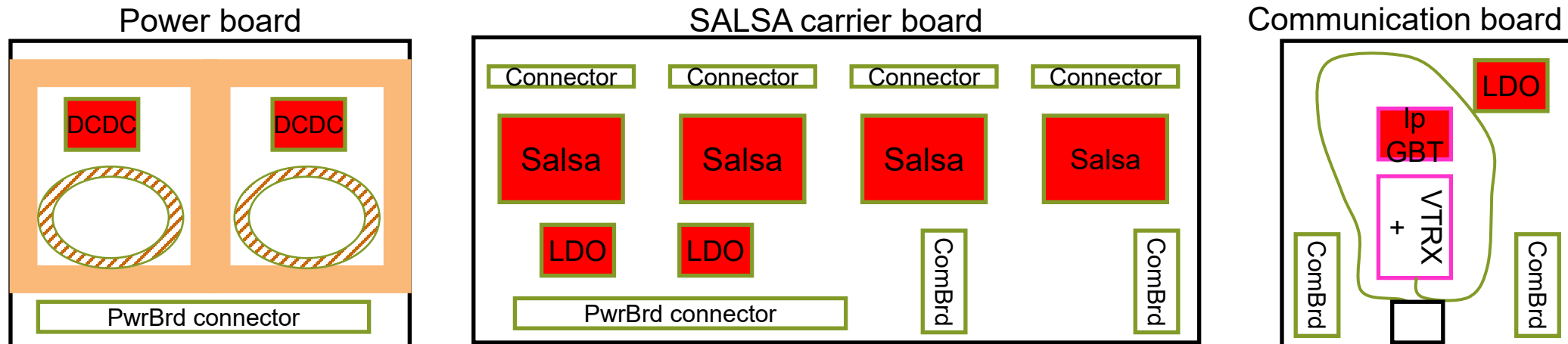


# Overview of MPGDs



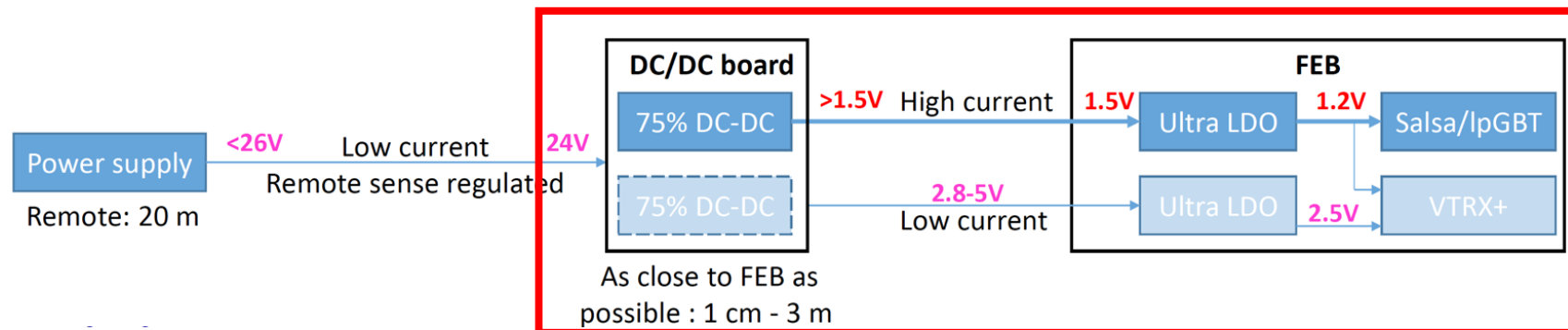
# MPGDs Readout Design

- 1. Unified Readout Architecture:** All MPGD subsystems (**BOT**, **ECT**, and **CyMBaL**) utilize a standardized streaming data path based on the **SALSA ASIC**, coupled with **IpGBT** and **VTRx+** for high-speed data transmission.
- 2. Subsystem Implementation Diversification:**
  - CyMBaL:** One common power board per tile (supporting 3 FEBs).
  - MPGD-ECT:** A sandwich-board design located on the module rims to minimize material budget.
  - MPGD-BOT:** A large spatial distribution of FEBs to cover long detector (7 FEB / 1.8 meter)
- 3. Integrated Thermal Management:** High-density heat loads are managed through a **shared water-cooling infrastructure**, using embedded aluminum or copper heatsinks tailored to the mechanical constraints of each tracker.



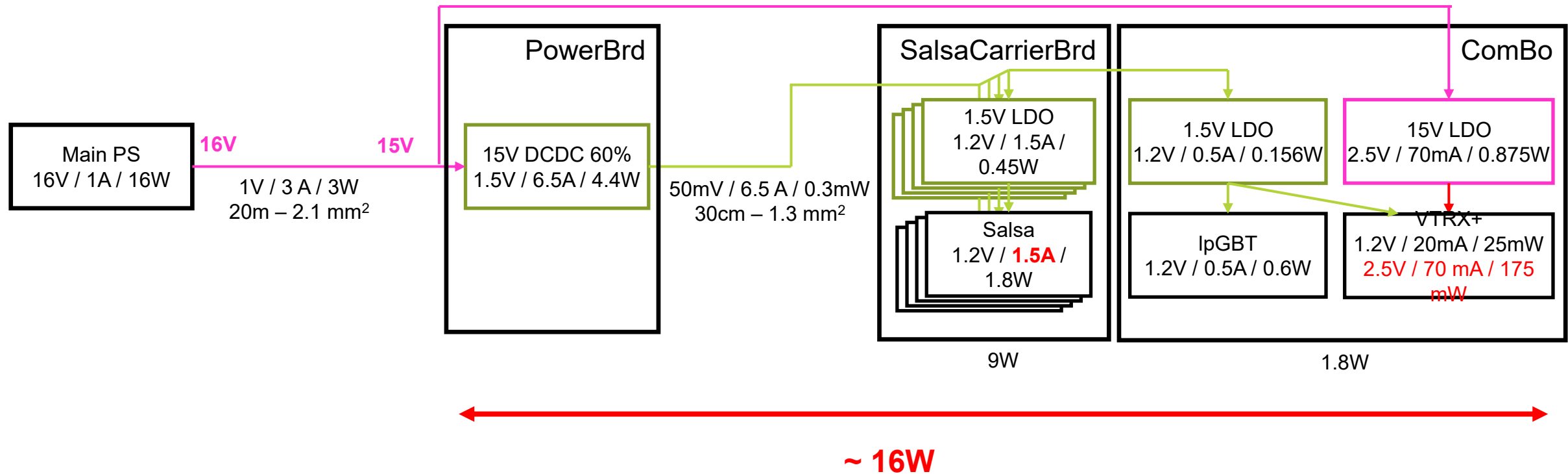
# Power requirement (all MPGDs)

- Review of powering scenarios
  - Likely increase of expected power consumption of SALSA (important uncertainty at this stage of the development)
  - 3 options are considered (SALSA current of 1A, **1.5A** and 2 A)
- The power chain is as follows
  - LV power supply – cable plant – DCDC power board – Salsa carrier and communication boards
  - The last actors in the power chain are LDO regulators producing clean power for ASICs
    - Salsa, IpGBT, VTRX+
  - Salsa requires high current 1.2V
  - IpGBT requires low current 1.2V
  - VTRX+ requires low current 2.5V and 1.2V

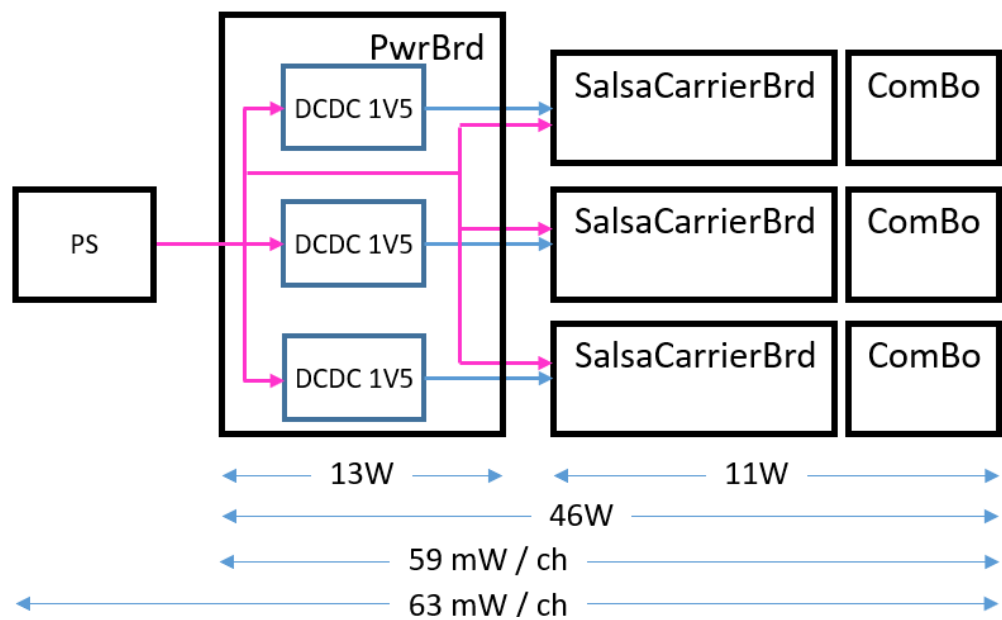


# Power distribution : single power board (1.5A SALSA current)

- Single power board for each FEB
- Example for 1.5 A total SALSA current
- Adapted to MPGD-ECT and MPGD-BOT



# Power distribution : shared power board (CyMBaL)



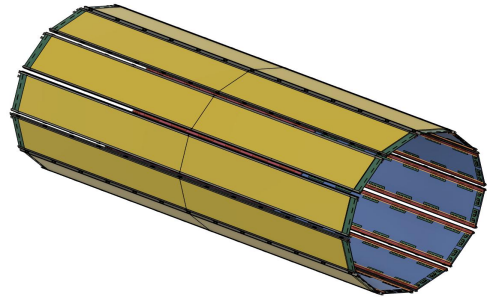
	Salsa 1.5A	
	Power	Pwr/ch
	W	mW
Salsa	1.8	28.1
Salsa carrier	9.0	35.2
Salsa carrier + ComBo	10.8	42.2
Power board	13.1	
3 x (Salsa carrier + ComBo) + PwrBrd	45.5	59.2
Power supply	48.5	63.1

- An important uncertainty coming from the consumption of Salsa
  - Safety factor is not applied
  - Varying the Salsa current gives the idea
- An Excel file exists that checks several hypotheses
  - Several parameters can be changed such as Salsa current, DCDC efficiencies, voltage drops, etc.
- Total power dissipation for CyMBaL (current new baseline scenario) :

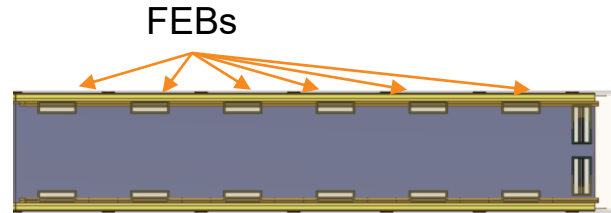
$59 \text{ mW/ch} \times 768 \times 48 = \mathbf{2.3 \text{ kW}}$



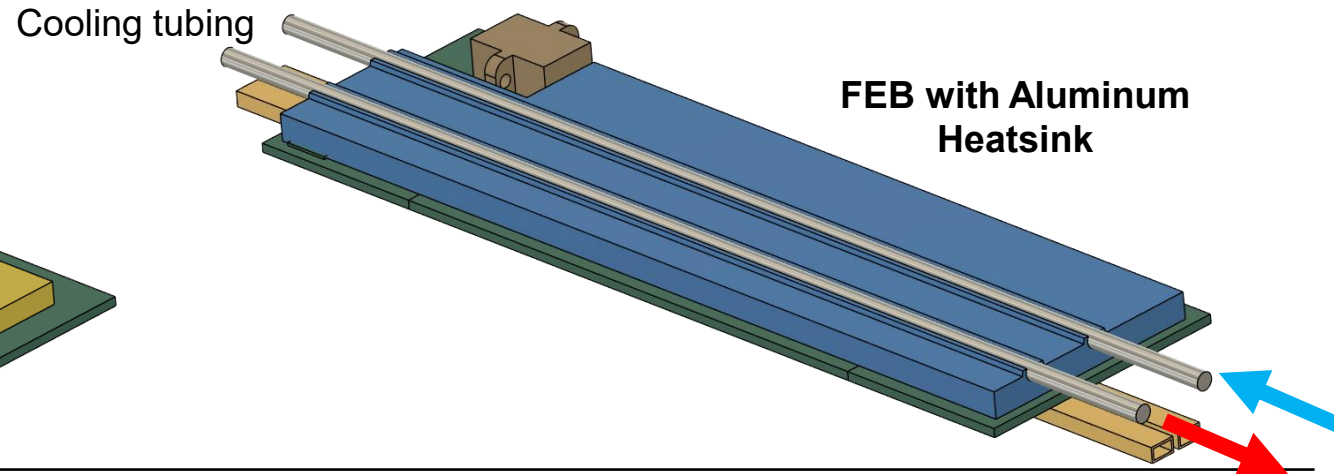
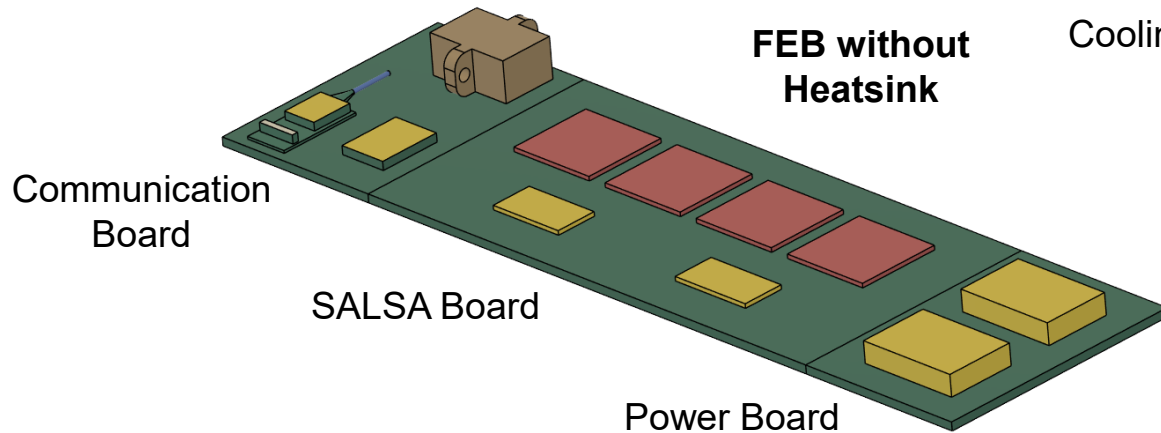
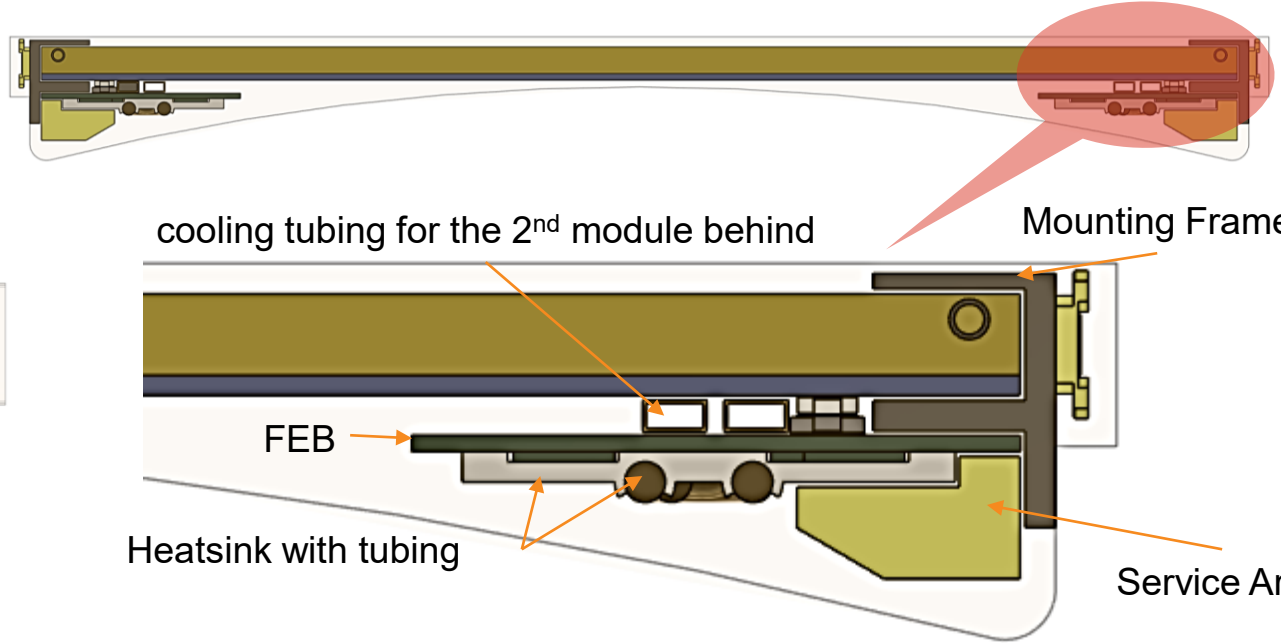
# MPGD-BOT module: FEB with cooling



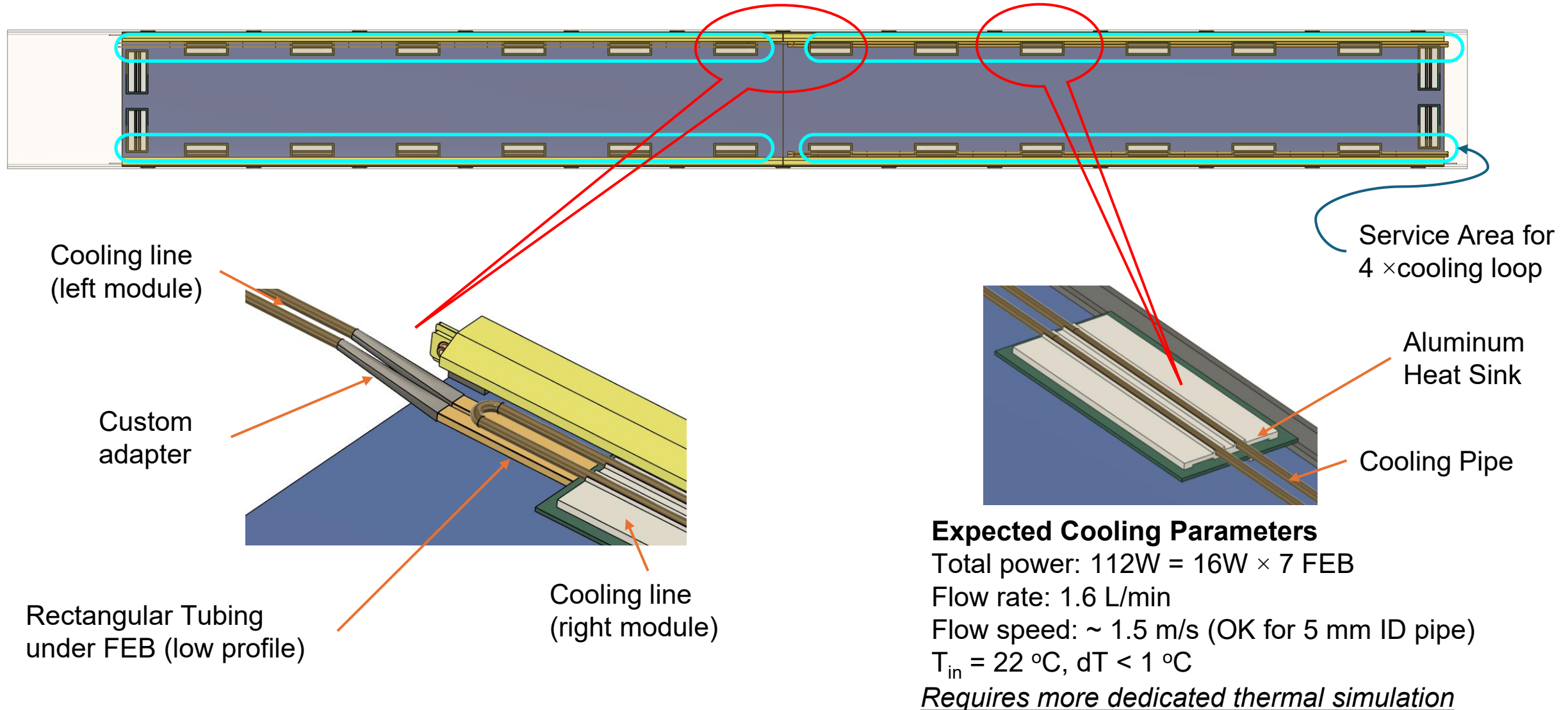
**MPGD Barrel Outer Tracker (MPGD-BOT)**



FEBs



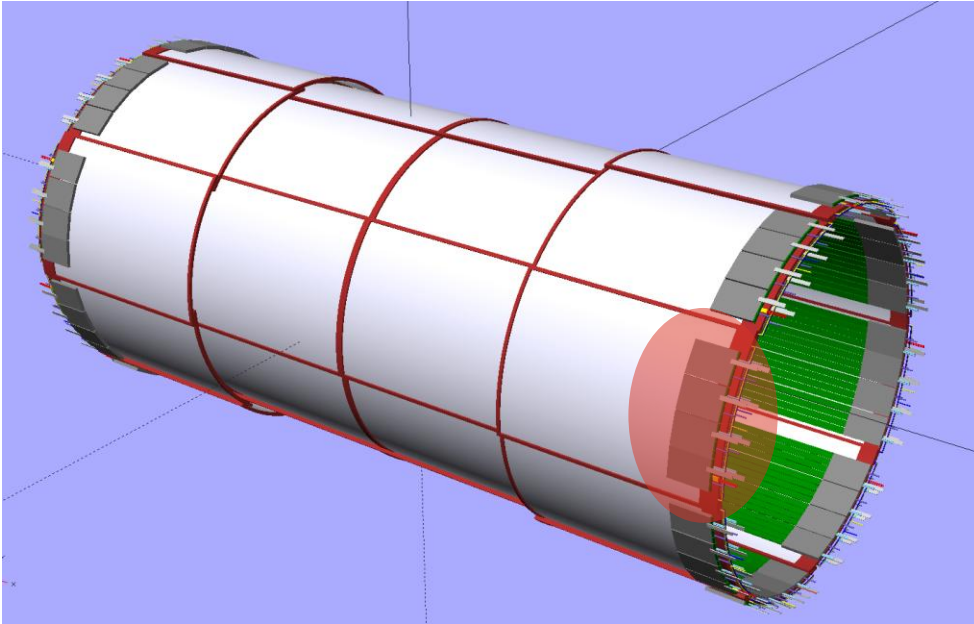
# MPGD-BOT module: FEB cooling design





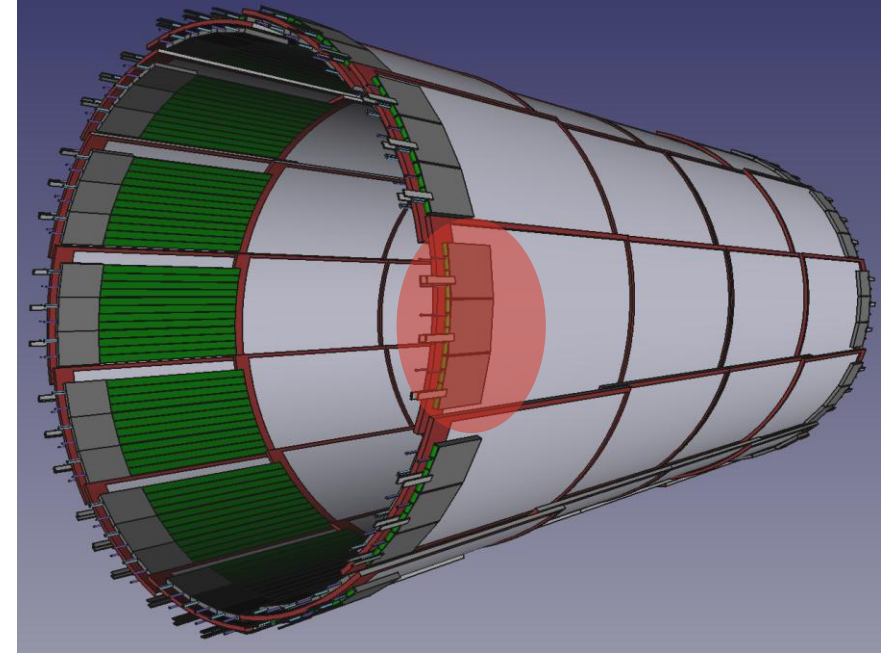
# CyMBaL – Updated design

In order to simplify installation and maintenance, the EIC Project proposed a change in design



## *Old design*

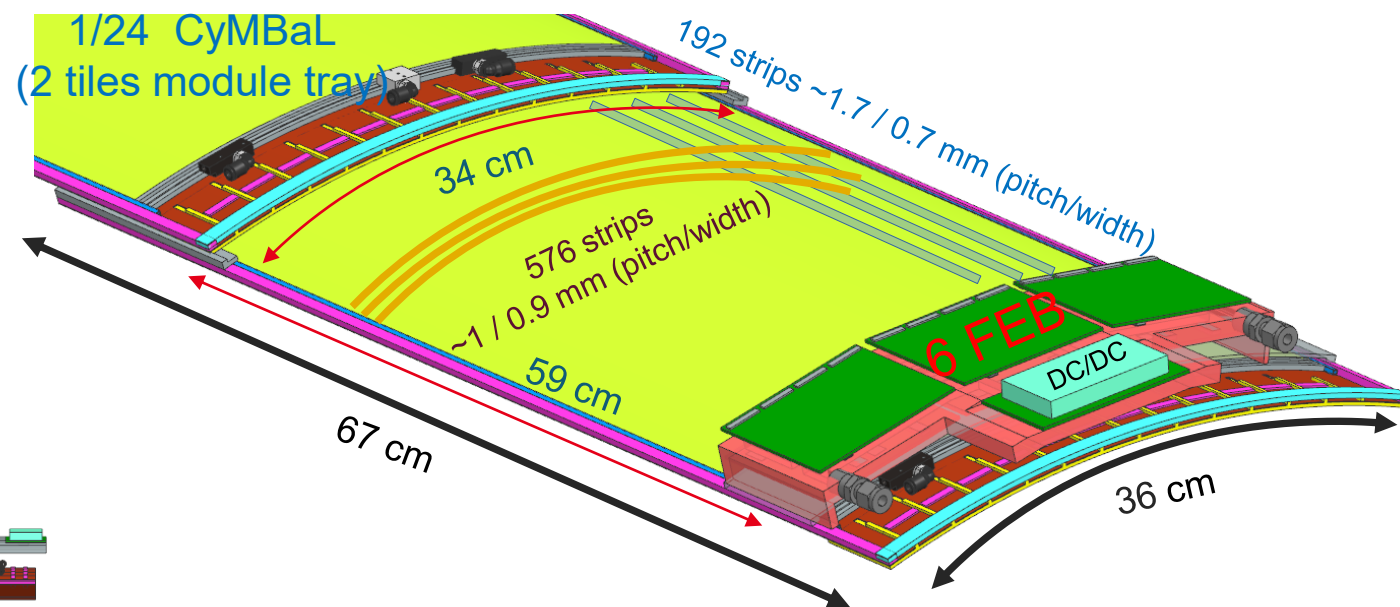
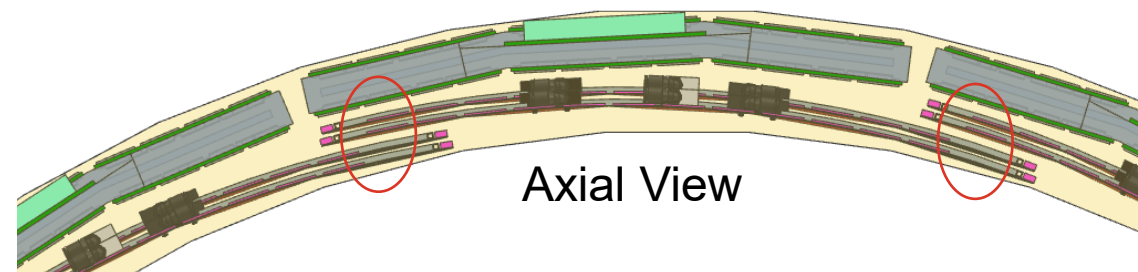
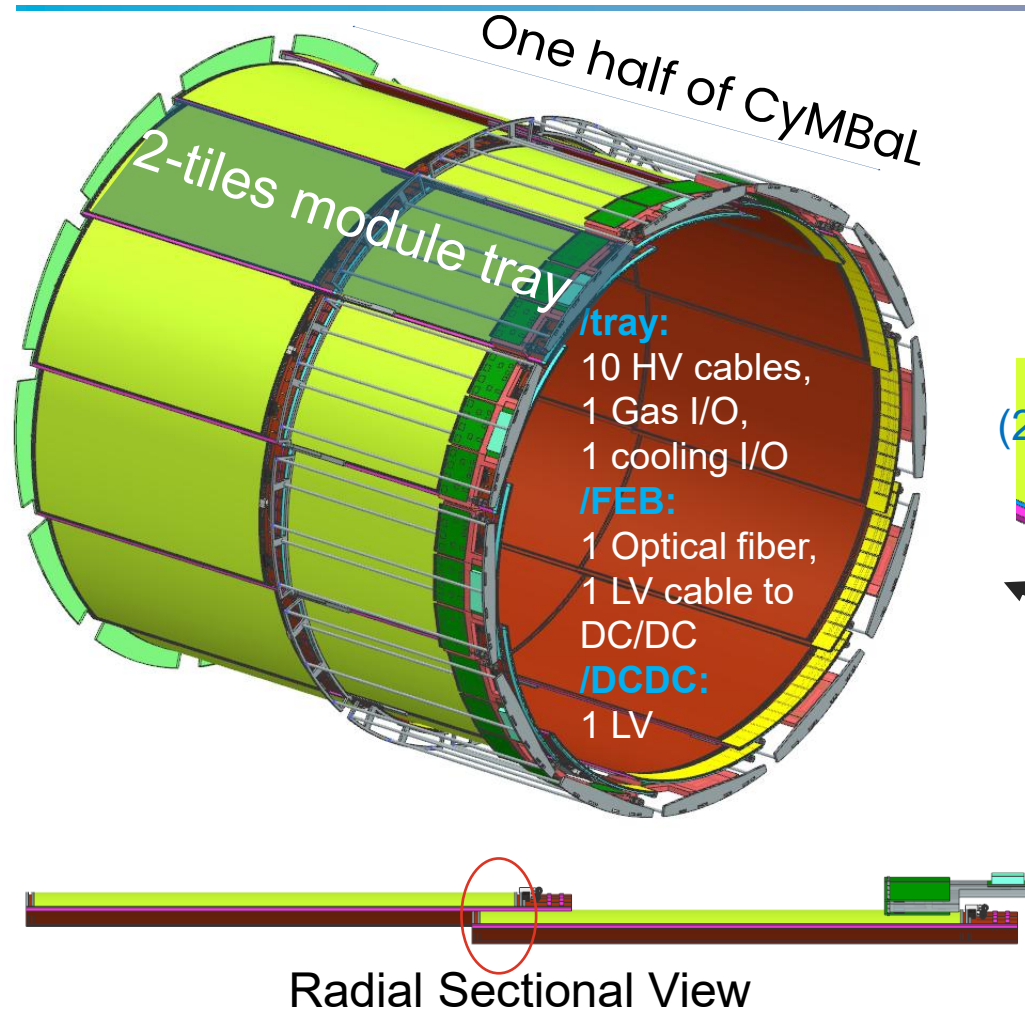
- **32 module: 8 modules in  $\phi$  times 4 modules in z**
- Overlaps in  $\phi$  and in z for hermeticity
- 1024 readout channels/module
- 4 FEB per module
- 32K readout channels



## *New design (2025)*

- **48 module: 12 modules in  $\phi$   $\times$  4 modules in z**
- Overlaps in  $\phi$  and in z for hermeticity
- 768 readout channels/module
- 3 FEB per module
- **37k readout channels**

# CyMBaL – Detector Design

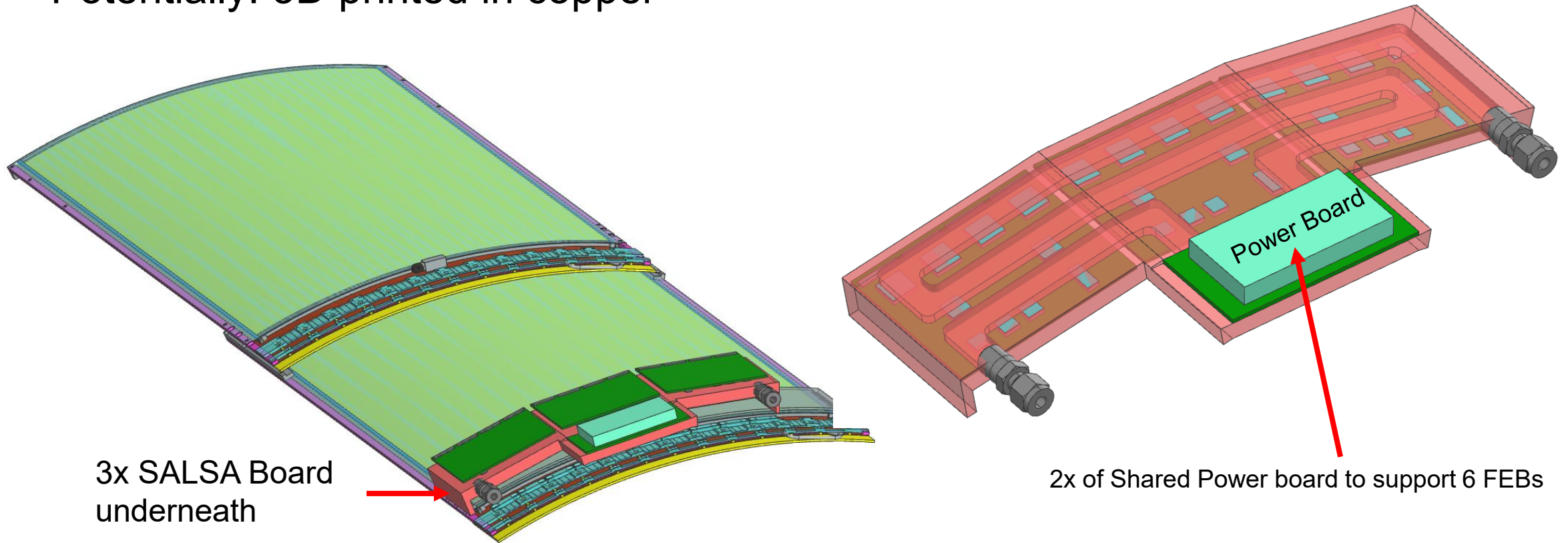


- Within the envelop, space only available for 3 FEBs per tile
- Each FEB will read (4 ASICs \* 64 ch/chip) 256 channels
- Total number of channels per tile limited at 768

# CyMBaL: Cooling Design

One Cooling Block per section → 2 Tiles (6x SALSA Board + 1x Power Board)

Potentially: 3D printed in copper





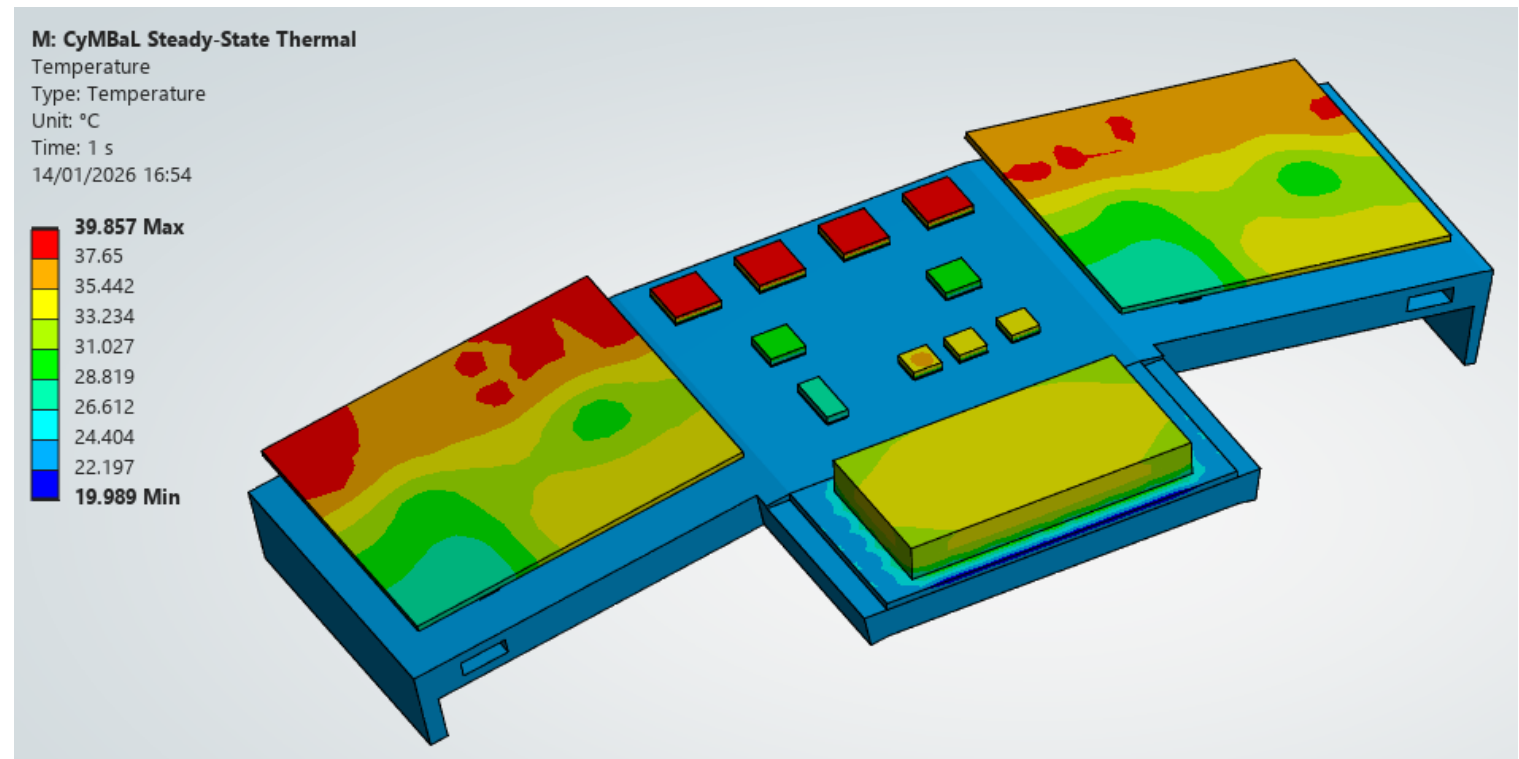
# CyMBaL: Thermal Simulation

SALSA current of 1.5 A:

Flow rate: 3 L/min

Temperature:  $T_{\text{in}} = 22^\circ\text{C}$ ,  $T_{\text{out}} = 22.66^\circ\text{C}$

Pressure:  $\Delta P$  0.03 bar

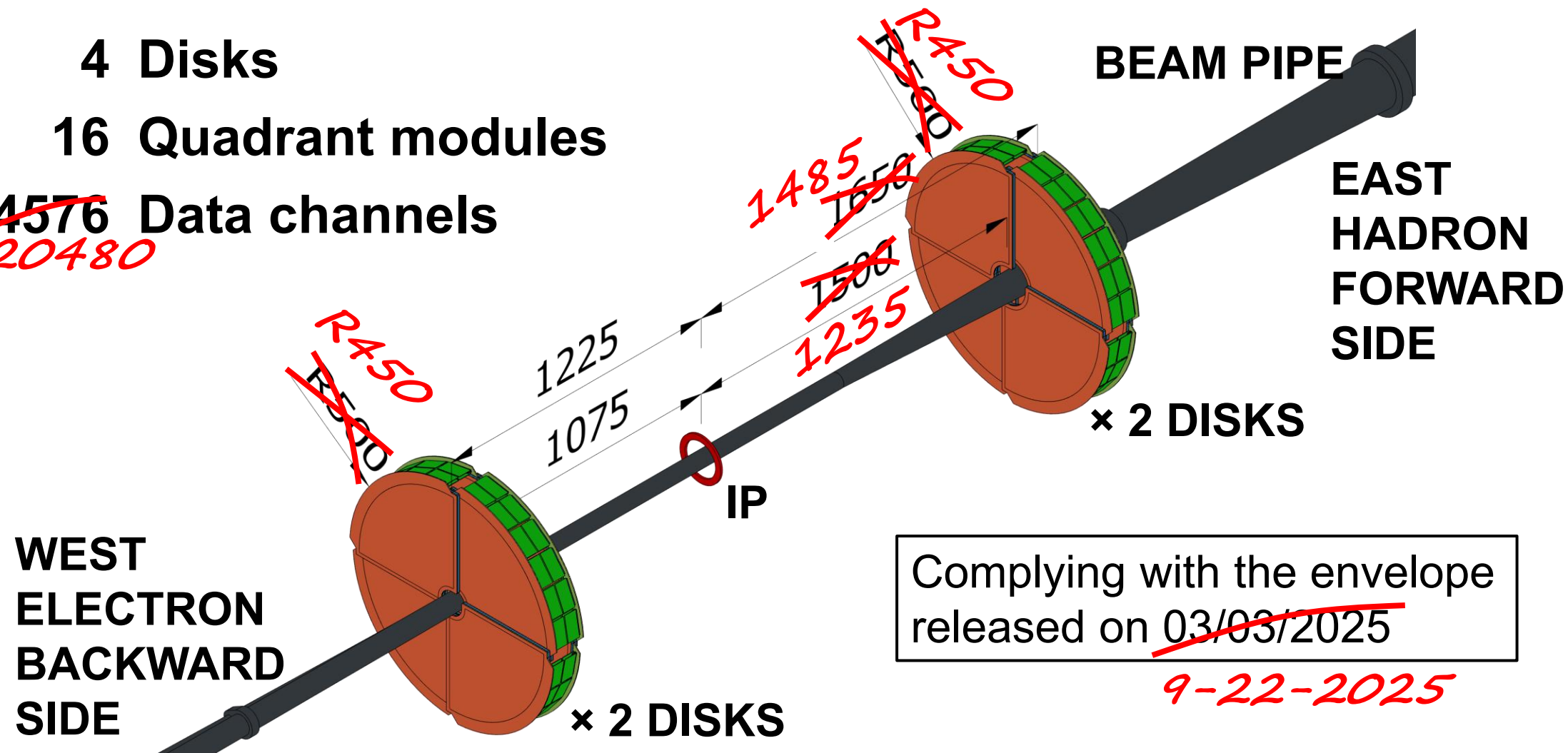


# MPGD-ECT Overview

4 Disks

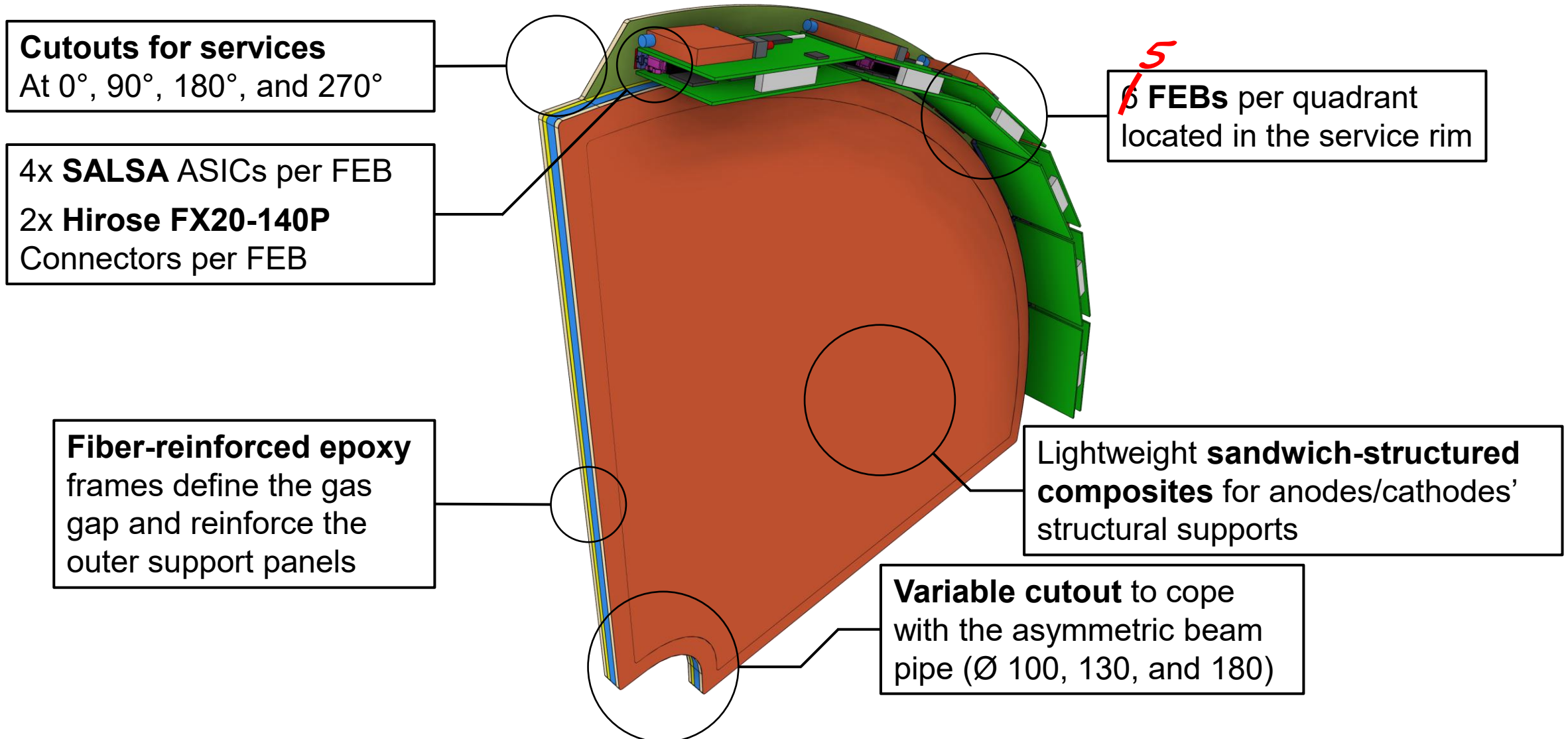
16 Quadrant modules

~~24576~~ Data channels  
*20480*

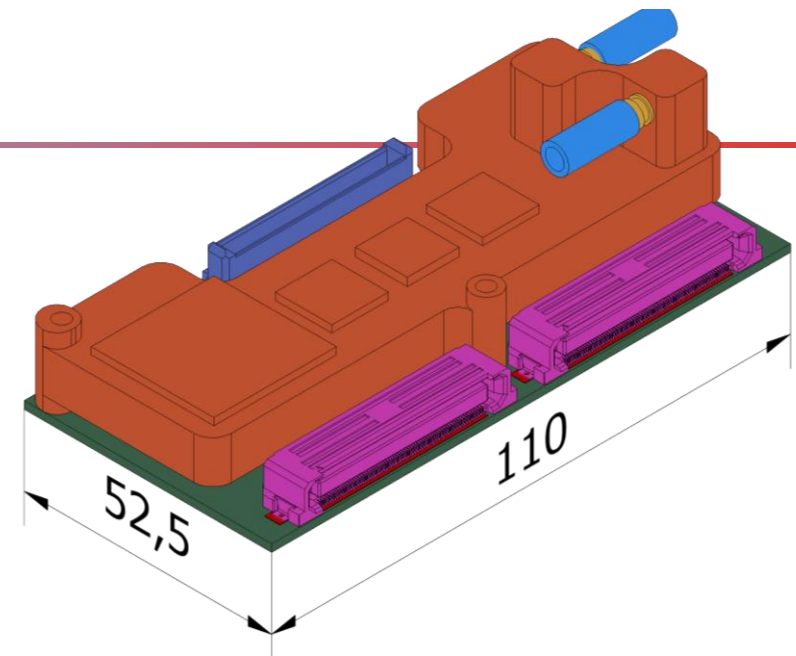
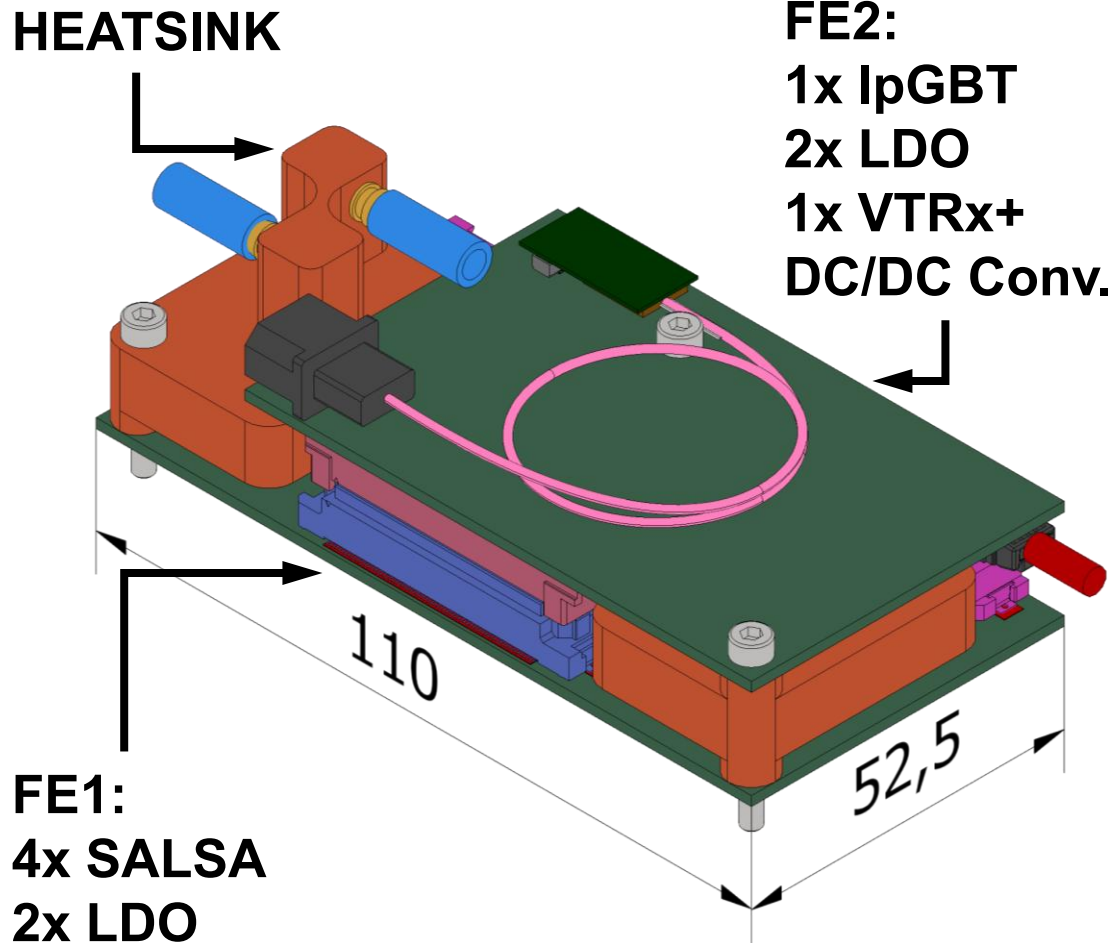




# Quadrant Concept



# New FEB Model

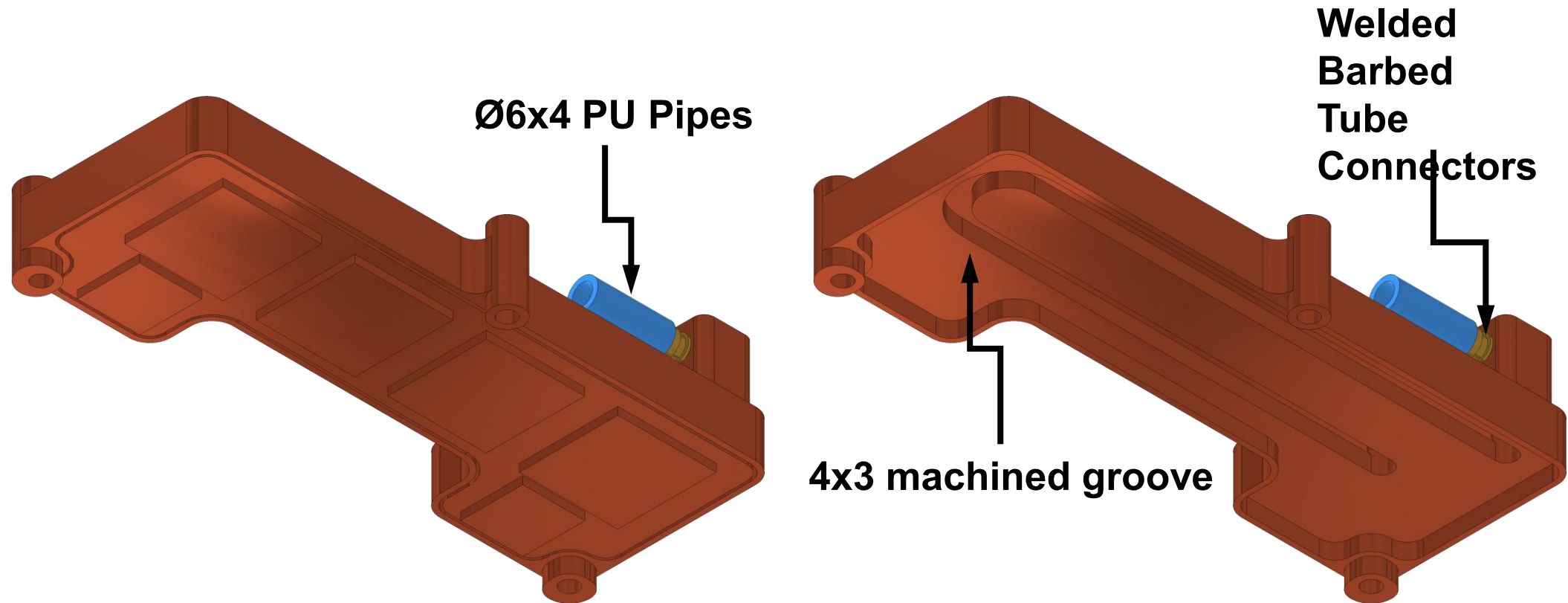


All 5 **heatsinks** in a module **connected in series** with pipes running close to the outer rim

No. 2 **Ø6x4 PU pipe per module** as inlet/outlet for the cooling chain

All major heat sources are mounted on the top/bottom face of FE1/FE2 to face the heatsink

# Heatsink Design



**Preliminary** proposal, no simulation has been run yet

Quite **bulky and difficult to manufacture** →

We will be working on **alternative cooling solutions** including 3D printed heatsink

# Summary of Power and Cooling Requirement

Assumption: **1.5A** current for SALSA chip => **16W per FEB**

	CyMBaL	MPGD-ECT	MPGD-BOT
Detector Module	48	16	24
FEBs per Module	3	5	14
Total FEBs	144	80	336
Total Power Req.	2.3 kW	1.28 kW	5.38 kW
Supply from	Both sides	Both sides	<b>East side</b>

Assumption: Water cooling, Heatsink with metal/plastic tubing,  $dT < 1\text{ }^{\circ}\text{C}$ ,  $\sim 3\text{ L/min}$

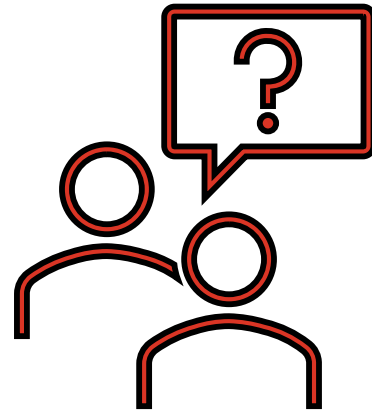
	CyMBaL	MPGD-ECT	MPGD-BOT
#FEB per cooling line	6	5	7
Cooling line per module	0.5	1	2
Total cooling line	24	16	48
Supply from	Both sides	Both sides	<b>East side</b>

# Summary

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1. There has been major design change for ECT and CymBaL.
2. Each subsystem has their own power/service/cooling design based on SALSA board which is still under development.
3. Preliminary water-cooled heatsink designs provide a baseline for heat dissipation across all MPGDs.
4. Critical Dependencies: Final cooling validation is pending the SALSA ASIC power specifications (1A vs. 2A uncertainty) and the application of appropriate safety margins.
5. Each subsystem will need more dedicated thermal simulation for the cooling design validation





**Questions?**

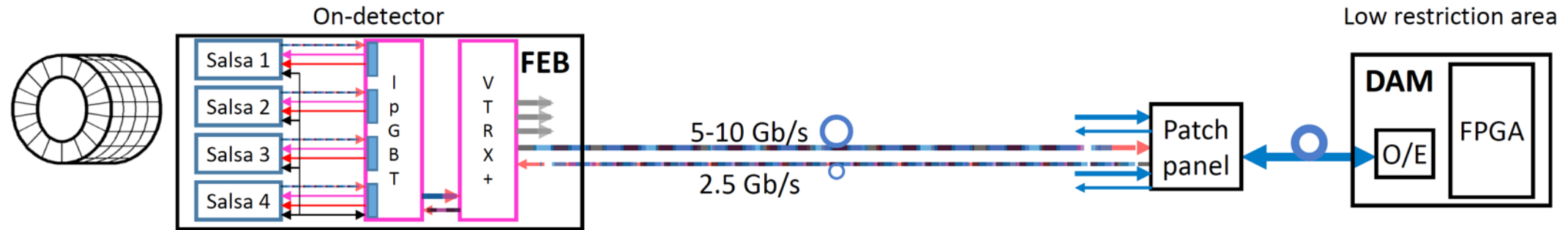
# Backup Slides

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# Services Estimates (MPGD-ECT)

Far from the detector (Before the manifolds/splitters)						
Service	# lines	Flow	Material	Fittings	Dimensions	Comment
Gas	4	IN	SS316/Cu	SS316/Brass	Ø8	1 per disk, 1 manifold per disk
	4	OUT	SS316/Cu	SS316/Brass	Ø8	1 per disk, 1 manifold per disk
Cooling	4	IN	PU	SS316	Ø12	1 per disk, 1 manifold per disk
	4	OUT	PU	SS316	Ø12	1 per disk, 1 manifold per disk
Dry air	4	IN	PU	SS316/Brass	Ø8	1 per disk, 1 manifold per disk (if humidity not controlled otherwise)
Data	96/80		Fiber optics		Ø2(?)	1 per FEB, 24/20 FEBs per disk in the 6/5 feb per module hypothesis
LV	96/80		Cable		Ø8(?)	1 per FEB, 24/20 FEBs per disk in the 6/5 feb per module hypothesis
HV	16		Multi-channelCable		Ø10(?)	1 per module (4 HV channels per module, 16 per disk), 4/5 kV highest voltage channel
GND	2		Copper braid		70 mm2	1 per side, if not provided otherwise
ENV	8		Cable + sensor		Ø8(?)	4 per side, 2 temperature + 2 humidity
Close to the detector (after the manifolds/splitters)						
Service	# lines	Flow	Material	Fittings	Dimensions	Comment
Gas	24	IN	PA11	SS316/Brass	Ø6	2 per module (8 per disk), modules could be connected in series to reduce # of ingoing/outgoing pipes
	24	OUT	PA11	SS316/Brass	Ø6	2 per module (8 per disk), modules could be connected in series to reduce # of ingoing/outgoing pipes
Cooling	16	IN	PU	SS316	Ø12	1 per module (4 per disk), All FEBs in each module are connected in series
	16	OUT	PU	SS316	Ø12	1 per module (4 per disk), All FEBs in each module are connected in series
Dry air	16	IN	PU	SS316/Brass	Ø6	1 per module (4 per disk)
Data	96/80		Fiber optics		Ø2(?)	1 per FEB, 24/20 FEBs per disk in the 6/5 feb per module hypothesis
LV	96/80		Cable		Ø8(?)	1 per FEB, 24/20 FEBs per disk in the 6/5 feb per module hypothesis
HV	16		Multi-channelCable		Ø10(?)	1 per module (4 HV channels per module, 16 per disk), 4/5 kV highest voltage channel
GND	2		Copper braid		70 mm2	1 per side, if not provided otherwise
ENV	8		Cable + sensor		Ø8(?)	4 per side, 2 temperature + 2 humidity

# CyMBaL – Readout electronics



Short pigtail / on board

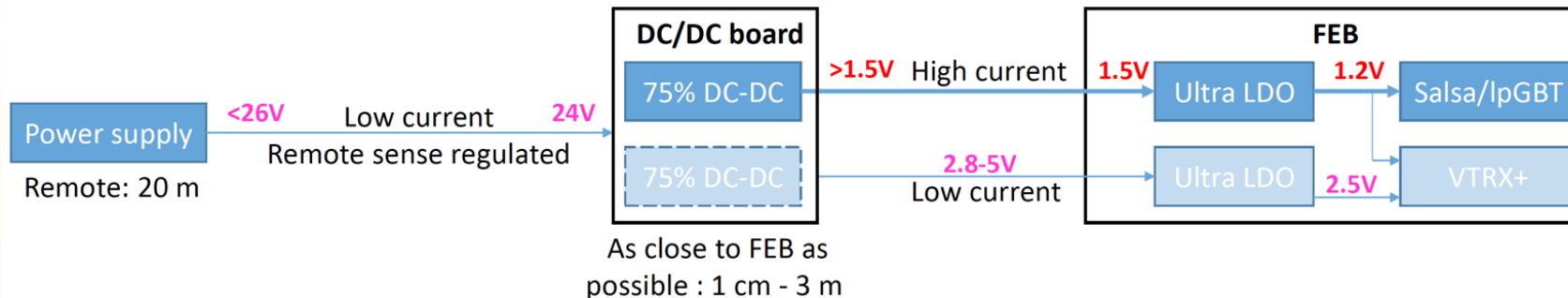


Fibers of adapted length between patch panels



Short pigtail / on board

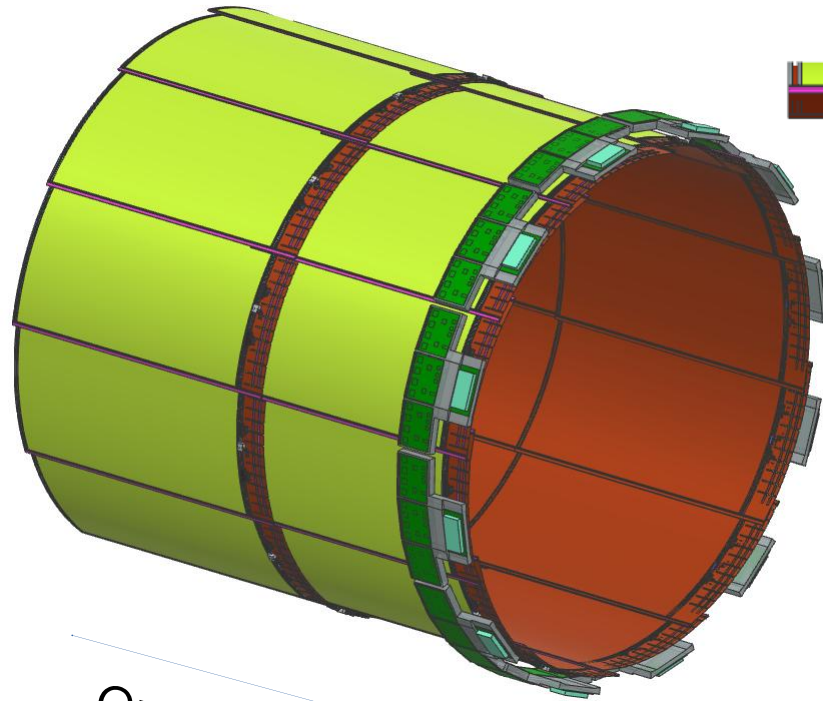
## FEB LV Powering scheme



## Cooling

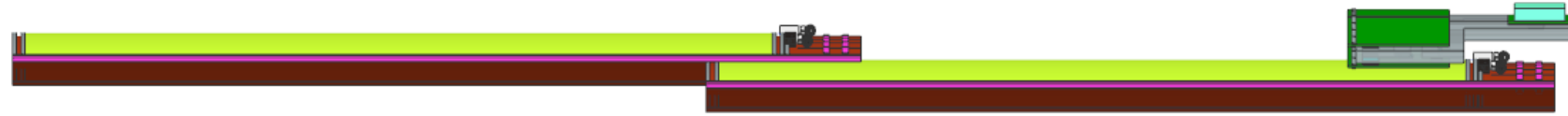
Current estimates: 18 deg water loop to cool each module, i.e. 3 (FEBs) x 2 (tiles) + DCDC is sufficient

# CyMBaL – Layout

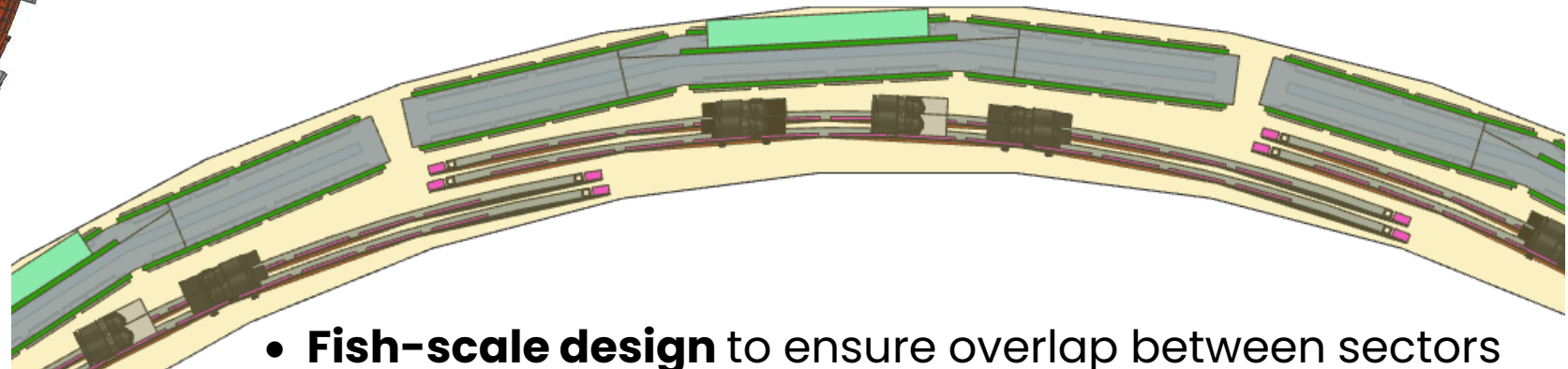


One half of CyMBaL

Micro-coaxial flat cables will bring signals from the inner tiles to the FEBs



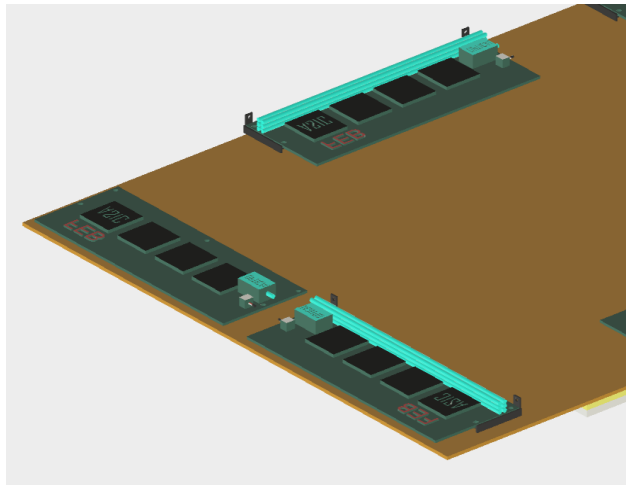
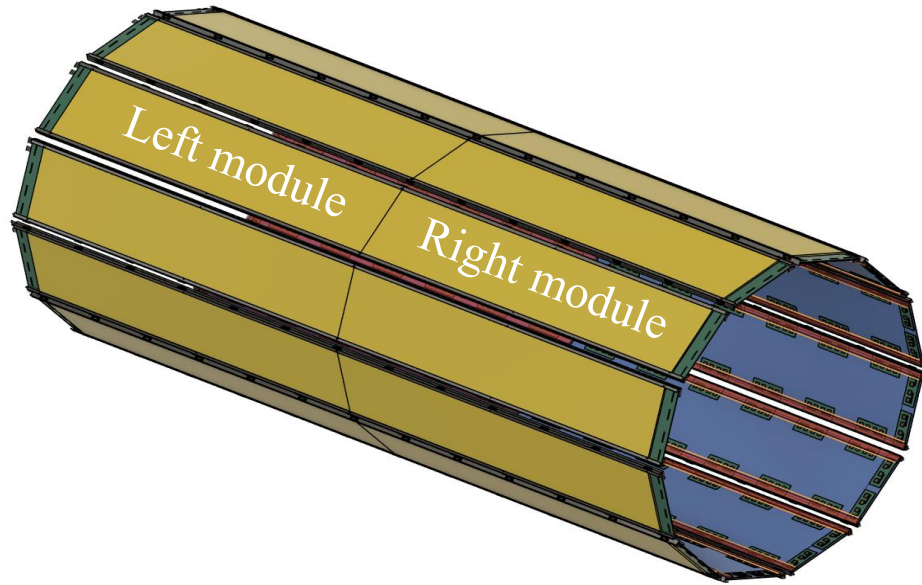
The two tiles in each module overlap in Z of about 4 cm



- **Fish-scale design** to ensure overlap between sectors
- Sectors overlap in phi of about 4 cm
- The 3 FEBs of the inner modules stacked on top of the 3 FEBs of the outer modules



# MPGD-BOT: Services

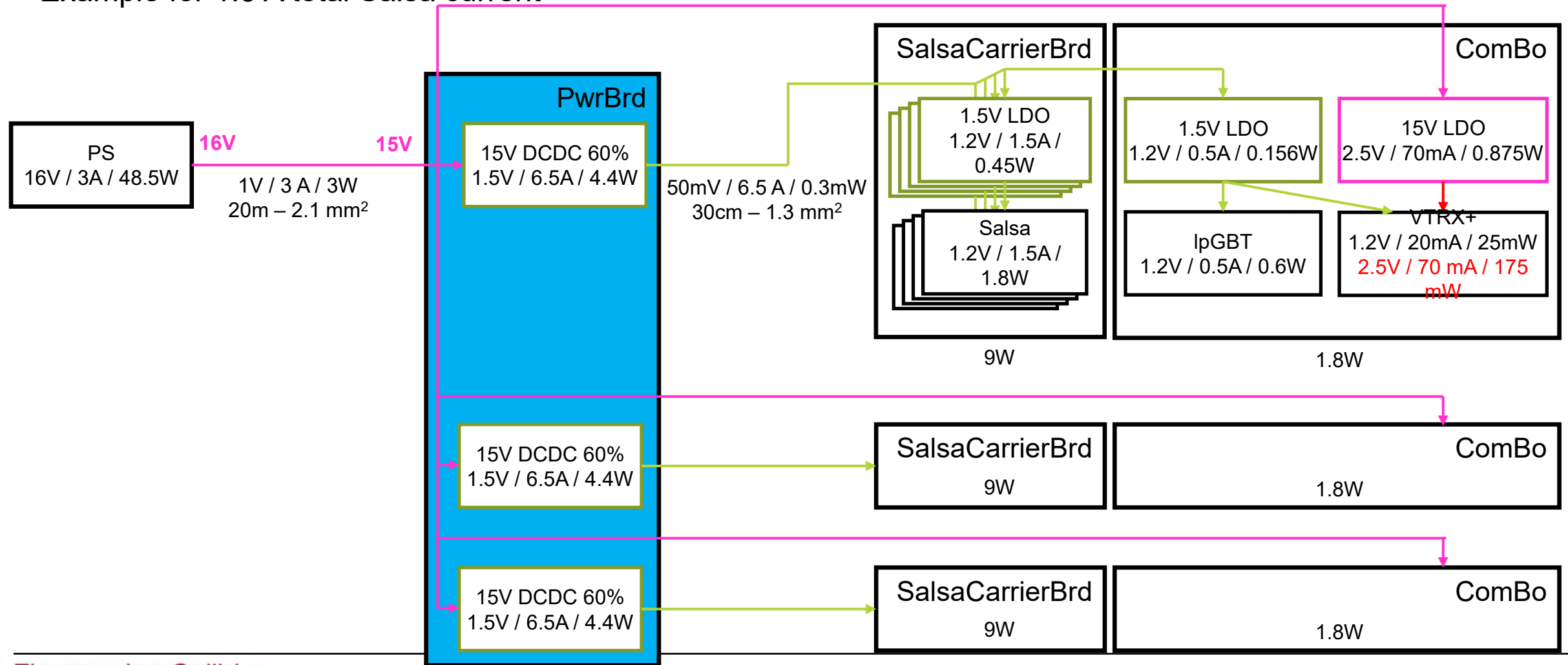


Service/Parts	Per Module	Total	Parameter
Frontend Boards (FEBs)	14	336	256 Channel / FEB
High Voltage	1 (through divider)	24	3.2 mm OD
Low Voltage	14	336	6 mm OD
Gas lines	2	48	3 mm ID, 4 mm OD
Cooling	4	96	6 mm ID, 8 mm OD
Data Cable	14	336	Optical Fiber
Environment Sensor	2	48	Temp. & Humidity
Ground			Depends on grounding plan
Power	225W	5400W	Based on 16W/board

- ❖ Parameters of service line are subject to change as FEB design progresses.
- ❖ The cooling requirement has not yet been finalized.
- ❖ The current cooling approach utilizes water cooling with a heatsink.

# CyMBaL Power distribution : Shared power board

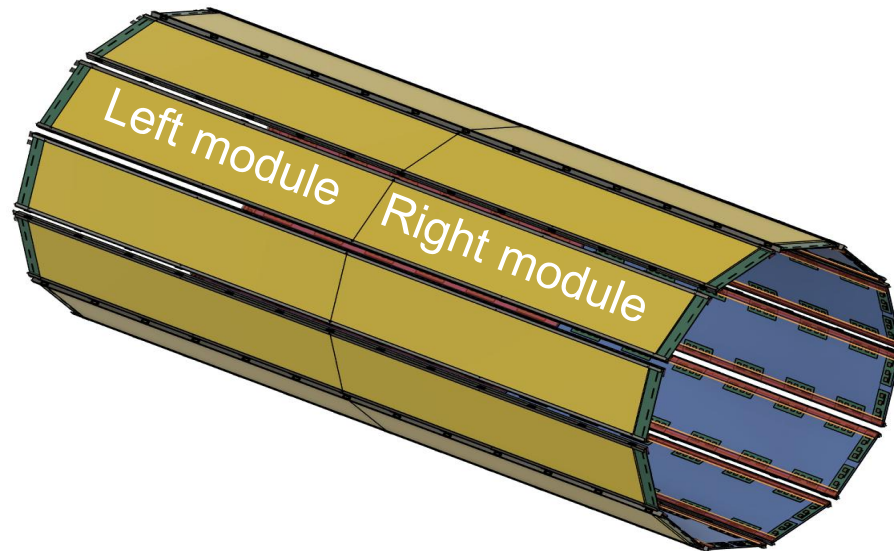
- Shared power board for the 3 FEBs of a tile
- Example for 1.5 A total Salsa current



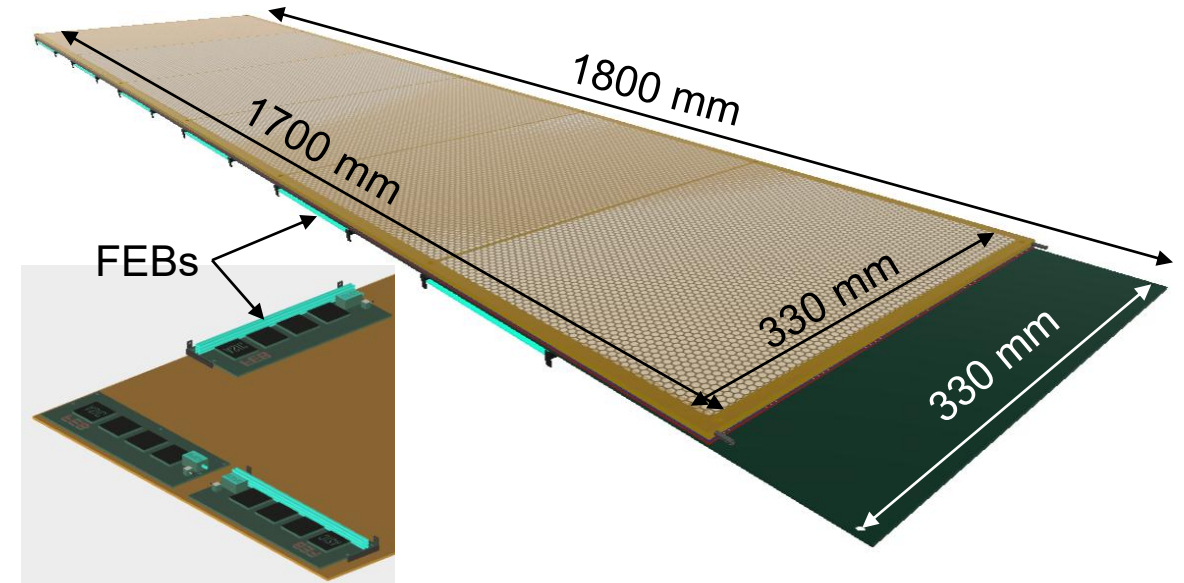
# MPGD-BOT Design

## 24 planar detector modules

- ❖ 2 sectors in z made of left and right planar modules
- ❖ 12 modules in  $(r \times \phi)$  arranged in dodecagon geometry
- ❖ Total readout electronic channels  $\sim 80K$

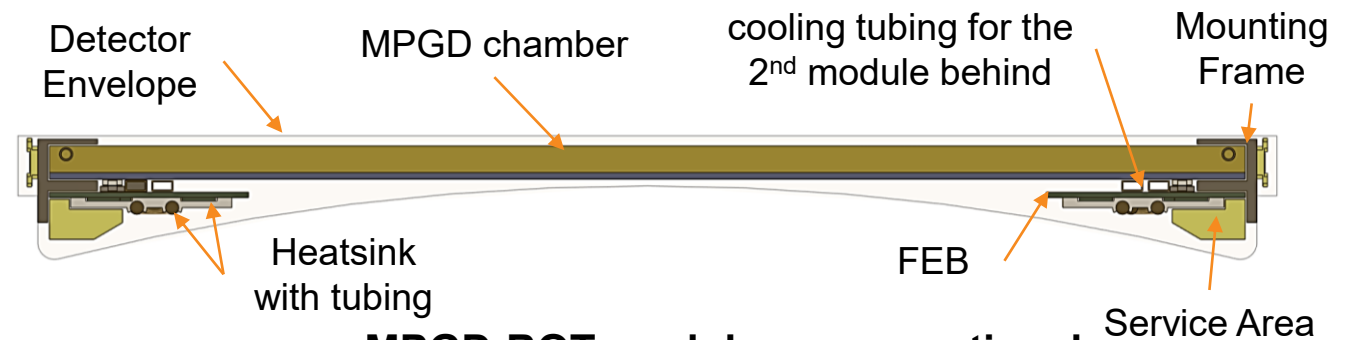


**MPGD Barrel Outer Tracker (MPGD-BOT)**



**MPGD-BOT module**

<https://eic.jlab.org/Geometry/Detector/Detector-20240515102931.html>



**MPGD-BOT module cross sectional**

**view**